

## DS-10P PARQUET ADHESIVE

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### Product:

DS-10P is a ready to use solvent-free adhesive, with a high solids content.

Suitable for bonding most common types of parquet onto highly absorbant substrates and also tapis floors on wooden subfloors.



### Technical data:

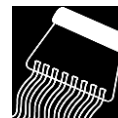
Base	Vinylacetate/Ethylene homopolymer
Curing system	Physical curing
Consistency	Paste
Colour	Pale brown
Density (DIN 53479)	Approx. 1,48 g/cm <sup>3</sup>
Brookfield viscosity (mPa s)	Approx. 57.500 (Brookfield HBT B/10)
Open time at 21°C and 50% R.H.	Approx. 30 – 45 minutes
Adjustability time at 21°C and 50% R.H.	Approx. 25 – 30 minutes
Set to load bearing	Min. 48 hrs
Sandpapering/finishing	Min. 24 hrs (in combination with nails) Min. 48 hrs (without nails)
Shear strength (DIN281b) wood/wood	> 5N/mm <sup>2</sup>
Temperature resistance	-20°C to +70°C (cured)
Durability against ageing	Good
Total solids content	Approx. 78%
Application rate	Depending on the subfloor 800 – 1000 g/m <sup>2</sup> by use of the Soudal-notched trowel for parquet

\* This varies according to ambient conditions such as temperature, humidity, substrate etc.

### Characteristics:

- Ready to use
- Low consumption/m<sup>2</sup>
- Solvent-free
- Very easy to apply
- Forms stable peaks once applied by a notched trowel or spreader comb
- Rapid build up of bond strength
- Rapid curing
- High final bond strength (according to DIN 281)
- Hard-elastic bond

Remark: The directives contained in this documentation are the result of our experiments and of our experience and have been submitted in good faith. Because of the diversity of the materials and substrates and the great number of possible applications which are out of our control, we cannot accept any responsibility for the results obtained. In every case it is recommended to carry out preliminary experiments.



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### Applications:

DS-10P is suitable for indoor bonding of many types of wooden floors such as mosaic, wood or laminate parquet (up to max. 250 x 50 mm), tapis 6-8 mm (in combination with nails), multi-layer or pre-finished parquet and laminates.

Not suitable for bonding beech (and) or exotic wood (hard wood).

Suitable for indoor use on highly absorbant subfloors of wood, chipboard and OSB Board (large particle size chipboard). For large and thin parquet only in combination with nails.

### Description:

DS-10P cures by means of evaporation of water from the adhesive. Fully cured (approx. 24 hrs. at 21°C and 50% RH) a hard-elastic and a non-shrinkable adhesive layer is formed, which is resistant to normal atmospheric humidity and temperature. The adhesive has excellent adhesion to practically all common porous substrates. DS-10P contains a minimal amount of water, which greatly reduces the risk of deforming the parquet to a minimum.

### Shelf-life:

12 months in unopened packaging in a cool and dry storage place at temperatures between +5°C and +25°.

### Substrate:

Before installation of the parquet, the substrate should be checked to ensure it is suitable. Check the moisture content throughout the entire thickness of the substrate with a carbide or electric hygrometer. The moisture content must be as recommended by the flooring manufacturer (generally max. 2% for sand cement substrates).

Do not use DS-10P on substrates, which contain anhydrite or magnesium.

Use **Soudal MS-30P** for these substrates.

DS-10P should be applied to an even, dry, clean and smooth substrate, which is also free from irregularities and cracks. Rests of old adhesives may affect the adhesion and must be removed mechanically. Loose or damaged surfaces must be repaired before the application of the adhesive using a suitable screed.

***A preliminary compatibility test is recommended on every surface.***

### Parquet:

The parquet flooring must be acclimatised for several days in the area where it is to be installed. Leave the parquet in its original packaging until installation to avoid any deformation. Check before installation that the moisture content of the wood is as recommended by the supplier, (generally 9% +/- 2%). If the humidity of the wood is more than 11%, installation is not recommended

Allow a gap of 1 to 1,5 cm around the perimeter of the laid parquet, including any columns or structures, which penetrate the floor.

### Applying the adhesive:

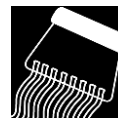
DS-10P should be acclimatised to room temperature before installation. Apply the adhesive to the surface by means of a suitable notched **Soudal** trowel. Do not apply more to the surface that can be covered with parquet within 30 minutes. Slide the parquet onto the adhesive layer and tap into place or tamp down with a rubber hammer.

A minimum of 80% contact coverage is required to ensure a proper adhesion. Loading the parquet with weights will improve the final bond strength. When bonding tapis onto a wooden subfloor the parquet must also be nailed.

Wait at least 48 hours before sanding and finishing the parquet, with nailed tapis, wait at least 24 hours.

Uncured DS-10P may be removed from tools and parquet with water. Cured adhesive must be removed mechanically.

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### Recommendations:

- Never install to substrates, which are not protected against possible rising damp.
- Do not apply the adhesive at temperatures below 15°C or above 25°C
- Minimum temperature of the substrate should be at least 15°C.
- Do not apply the adhesive when the relative humidity is above 75%.
- Never install onto a substrate which contains too much moisture or onto substrates with a higher humidity value than recommended by the wood supplier.
- Never install wood which is too dry (<7% humidity). This can expand at higher humidity and cause damage.
- Do not install if the walls and ceilings of the area are not dry (e.g. after plastering or painting etc.)
- Do not dilute the adhesive.

### Health and safety recommendations:

Apply the usual industrial hygiene precautions.  
Wear protective gloves.  
Consult the label for more information.

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